

Title (en)  
RESIN COMPOSITION, MOLDED BODY AND COMPOSITE MOLDED BODY

Title (de)  
HARZZUSAMMENSETZUNG, FORMKÖRPER UND VERBUNDFORMKÖRPER

Title (fr)  
COMPOSITION DE RÉSINE, CORPS MOULÉ ET CORPS MOULÉ COMPOSITE

Publication  
**EP 2535378 A4 20150902 (EN)**

Application  
**EP 11742287 A 20110210**

Priority  
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Abstract (en)  
[origin: EP2535378A1] In accordance with the present invention, by using a resin composition including lignin and a curing agent in which the lignin is soluble in an organic solvent and contained in the resin composition in an amount of from 10 to 90% by mass, there are provided a molded product and a composite molded product which are obtained from plant resources as a main raw material and to which a good flame retardance and a good antibacterial property are imparted.

IPC 8 full level  
**C08L 97/00** (2006.01); **C08G 18/64** (2006.01); **C08G 18/73** (2006.01); **C08G 59/40** (2006.01); **C08G 59/62** (2006.01); **C08H 7/00** (2011.01); **C08H 8/00** (2010.01); **C08L 63/00** (2006.01)

CPC (source: EP KR US)  
**C08G 18/6492** (2013.01 - EP KR US); **C08G 18/73** (2013.01 - EP KR US); **C08G 59/40** (2013.01 - KR); **C08G 59/62** (2013.01 - KR); **C08G 59/621** (2013.01 - EP KR US); **C08G 63/91** (2013.01 - KR); **C08H 6/00** (2013.01 - EP KR US); **C08H 8/00** (2013.01 - EP KR US); **C08J 5/00** (2013.01 - KR); **C08L 63/00** (2013.01 - EP KR US); **C08L 97/00** (2013.01 - KR); **C08L 97/005** (2013.01 - EP KR US); **C08L 2201/02** (2013.01 - KR)

C-Set (source: EP US)  
1. **C08L 63/00** + **C08L 97/00**  
2. **C08L 97/005** + **C08L 63/00**

Citation (search report)  
No further relevant documents disclosed

Cited by  
WO2019076893A1; FR3072386A1; EP3192825A4; EP3470454A1; AU2018208759B2; US10138377B2; US11524974B2; WO2019081819A1

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DOCDB simple family (publication)  
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